*Functional Safety Information*

# *LMR54430-Q1 and LMR54450-Q1 Functional Safety FIT Rate, FMD and Pin FMA*

## Table of Contents

# 1 Overview

This document contains information for the LMR54430-Q1 and LMR54450-Q1 (HSOP package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device
- Pin failure mode analysis (Pin FMA)

Figure 1-1 shows the device functional block diagram for reference.

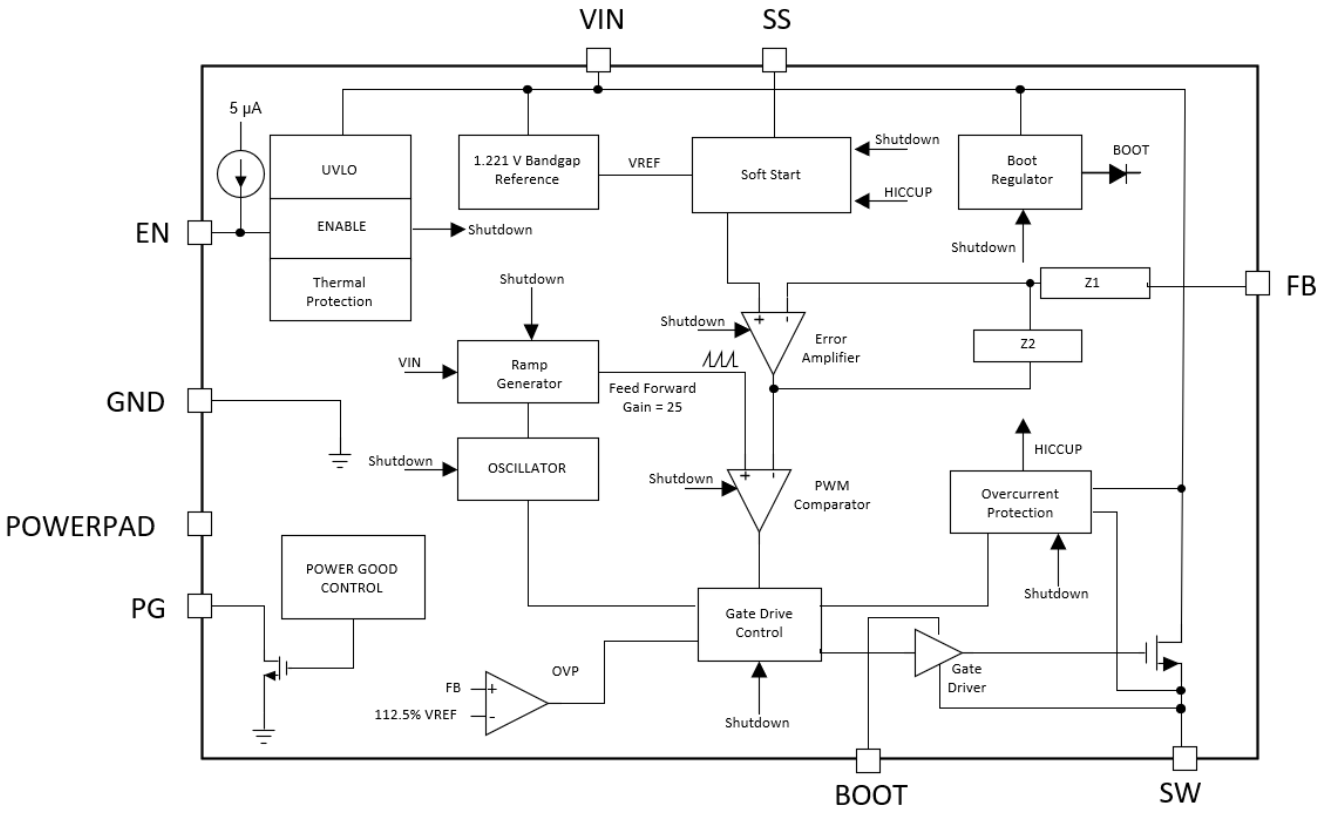


**Figure 1-1. Functional Block Diagram**

The LMR54430-Q1 and LMR54450-Q1 were developed using a quality-managed development process, but were not developed in accordance with the IEC 61508 or ISO 26262 standards.

**ADVANCE INFORMATION for preproduction products; subject to change without notice.**

## 2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for the LMR54430-Q1 and LMR54450-Q1 based on two different industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on the Siemens Norm SN 29500-2

**Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11**

| FIT IEC TR 62380 / ISO 26262 | FIT (Failures Per $10^9$ Hours) |
|---|---|
| Total Component FIT Rate | 17 |
| Die FIT Rate | 9 |
| Package FIT Rate | 8 |

The failure rate and mission profile information in Table 2-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 1000mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

**Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2**

| Table | Category | Reference FIT Rate | Reference Virtual $T_J$ |
|---|---|---|---|
| 5 | CMOS / BICMOS<br>analog / mixed signal, less than 50 V supply | 25 FIT | 55°C |

The Reference FIT Rate and Reference Virtual $T_J$ (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

# 3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for the LMR54430-Q1 and LMR54450-Q1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

**Table 3-1. Die Failure Modes and Distribution**

| Die Failure Modes | Failure Mode Distribution (%) |
|---|---|
| SW No output | 50% |
| SW output not in specification - voltage or timing | 40% |
| SW power FET stuck on | 5% |
| PGOOD false trip, fails to trip | 5% |

The FMD in Table 3-1 excludes short circuit faults across the isolation barrier. Faults for short circuit across the isolation barrier can be excluded according to ISO 61800-5-2:2016 if the following requirements are fulfilled:

1. The signal isolation component is OVC III according to IEC 61800-5-1. If a SELV/PELV power supply is used, pollution degree 2/OVC II applies. All requirements of IEC 61800-5-1:2007, 4.3.6 apply.
2. Measures are taken to ensure that an internal failure of the signal isolation component cannot result in excessive temperature of its insulating material.

Creepage and clearance requirements should be applied according to the specific equipment isolation standards of an application. Care should be taken to maintain the creepage and clearance distance of a board design to ensure that the mounting pads of the isolator on the printed-circuit board do not reduce this distance.

# 4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the LMR54430-Q1 and LMR54450-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to supply (see Table 4-5)

Table 4-2 through Table 4-5 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

**Table 4-1. TI Classification of Failure Effects**

| Class | Failure Effects |
|---|---|
| A | Potential device damage that affects functionality. |
| B | No device damage, but loss of critical functionality. |
| C | No device damage, but loss of minor or performance degradation. |
| D | No device damage, no impact to functionality or performance. |

Figure 4-1 shows the LMR54450-Q1 and LMR54430-Q1 pin diagram. For a detailed description of the device pins please refer to the *Pin Configuration and Functions* section in the LMR54450-Q1 and LMR54430-Q1 data sheet.

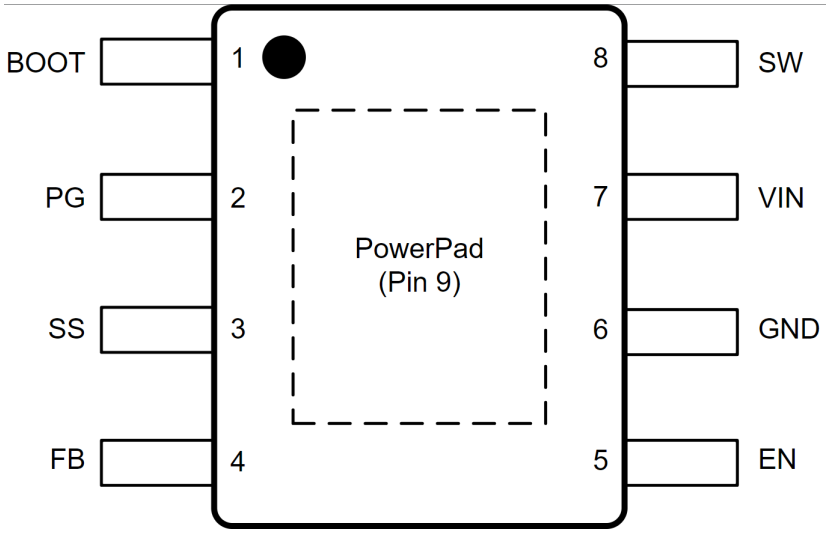


**Figure 4-1. Pin Diagram**

**Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground**

| Pin Name | Pin No | Description of Potential Failure Effect(s) | Failure Effect Class |
|---|---|---|---|
| BOOT | 1 | $V_{OUT}$ = 0 V | B |
| PG | 2 | Normal operation without PG indication (PG is always low in this case). | D |
| SS | 3 | $V_{OUT}$ = 0 V | B |
| FB | 4 | $V_{OUT}$ >> than programmed output voltage | B |
| EN | 5 | $V_{OUT}$ = 0 V | B |
| GND | 6 | Normal operation | D |
| VIN | 7 | $V_{OUT}$ = 0 V, no input voltage | B |
| SW | 8 | $V_{OUT}$ = 0 V, damage to high-side FET | A |

**Table 4-3. Pin FMA for Device Pins Open-Circuited**

| Pin Name | Pin No | Description of Potential Failure Effect(s) | Failure Effect Class |
|---|---|---|---|
| BOOT | 1 | $V_{OUT}$ = 0 V | B |
| PG | 2 | Normal operation without PG indication (PG is always high in this case). | D |
| SS | 3 | Normal operation (internal soft start) | D |
| FB | 4 | $V_{OUT}$ >> than programmed output voltage | B |
| EN | 5 | Normal operation | D |
| GND | 6 | $V_{OUT}$ = 0 V | B |
| VIN | 7 | $V_{OUT}$ = 0 V | B |
| SW | 8 | $V_{OUT}$ = 0 V | B |

**Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin**

| Pin Name | Pin No | Description of Potential Failure Effect(s) | Failure Effect Class |
|---|---|---|---|
| BOOT | 1 | $V_{OUT}$ = 0 V | B |
| PG | 2 | $V_{OUT}$ = 0 V, no start-up due to SS pin pulled low | B |
| SS | 3 | Voltage mode control loop is open, no regulation | B |
| FB | 4 | $V_{OUT}$ = 0 V, the EN pin is pulled low by small FB resistors. | B |
| EN | 5 | $V_{OUT}$ = 0 V | B |
| GND | 6 | $V_{OUT}$ = 0 V, no input voltage | B |
| VIN | 7 | $V_{OUT}$ = $V_{IN}$ | B |
| SW | 8 | $V_{OUT}$ = 0 V | B |

**Table 4-5. Pin FMA for Device Pins Short-Circuited to supply**

| Pin Name | Pin No | Description of Potential Failure Effect(s) | Failure Effect Class |
|---|---|---|---|
| BOOT | 1 | $V_{OUT}$ = 0 V. BOOT ESD clamp runs current to destruction. | A |
| PG | 2 | If $V_{IN}$ exceeds 7 V, damage occurs. | A |
| SS | 3 | If $V_{IN}$ exceeds 7 V, damage occurs. | A |
| FB | 4 | If $V_{IN}$ exceeds 7 V, damage occurs. $V_{OUT}$ = 0 V | A |
| EN | 5 | $V_{OUT}$ = 0 V. If $V_{IN}$ exceeds 6 V, damage occurs. | A |
| GND | 6 | $V_{OUT}$ = 0 V, no input voltage | B |
| VIN | 7 | Normal operation | D |
| SW | 8 | $V_{OUT}$ = $V_{IN}$ | B |

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